

CYPRESS SEMICONDUCTOR

PRODUCT CHANGE NOTIFICATION

PCN: 990027

DATE: September 30, 1999

Subject: Assembly Location, Molding Compound and Lead Frame Change, 28 lead SOIC

To:

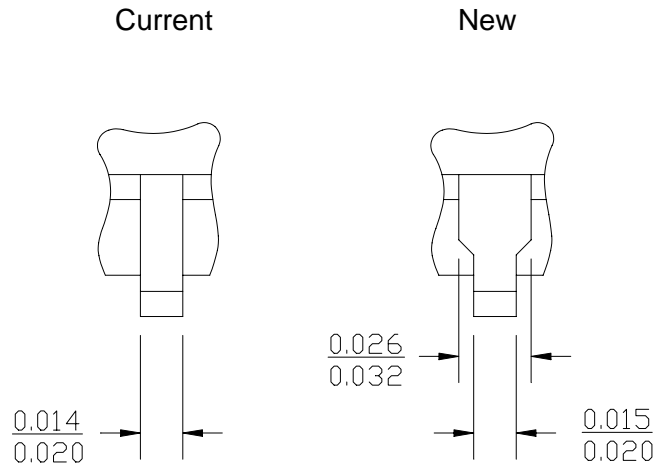
Category:

Level:

Description of change:

Cypress has qualified three changes that effect 28 lead SOIC (package code 'SN') plastic packages:

1. Cypress Semiconductor Philippines (CSPI) has been qualified as the primary source to assemble 28 Lead SOIC (package code 'SN') plastic packages. Qualification report QTP 99151 is attached.
2. The inner dimension of the lead shoulder (lead width extending from the package outline, see figure below) has been changed to provide increased lead integrity. This change is compliant with JEDEC standard MO-059 and was qualified on QTP 99151 attached.



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3. Cypress has qualified a molding compound change that will be used for 28/24/20 lead SOIC packages assembled at Cypress's Philippines (CSPI) assembly plant. Cypress will be converting production from Sumitomo EME6300HR to Sumitomo EME6600CR on the 28 Lead SOIC (package code 'SN') due to its improved lower absorption and susceptibility to moisture. QTP 99101 attached. The moisture sensitivity level (MSL) is 1, the same as the previous molding compound.

Cypress part numbers affected:

CY62256-*
CY62256L-*
CY62256LL-*
CY62256V-*
CY62256VL-*
CY62256VLL-*
CY6264*

all speeds, commercial and industrial temperature ranges, supplied in 28 Lead SOIC (package code 'SN') plastic packages.

Customer part numbers affected:

Benefit of change:

Increased assembly capacity, improved lead integrity and improved quality and reliability due to lower absorption/susceptibility to moisture.

Qualification status:

Complete. Qualification Reports # 99151 and # 99101 are attached.

Sample status:

Samples are available by contacting our local sales office.

Approximate Implementation Date:

Production release of the new material will be phased in immediately or as agreed per your contract terms and conditions.

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Response Required:

If the cover letter indicates that your company is designated as "Category A or Category C" and there are current orders pending, this form must be signed and returned as soon as possible. If acceptance is not received, delays in shipment may occur.

Category 'C' customers

If No response is received within 90 days change will be incorporated.

Category 'A' or Category 'C' customer:

Change accepted by: _____ Note: If Change is Not applicable to
your facility enter N/A

Print Name: _____ Company: _____

Title: _____ Date: _____

PCN Sent to: _____ Company: _____

*Fax signed approval to Jim Townsend at 408-943-4897 or reply by E-mail.
For any additional information regarding this change, contact your local sales representative.*

Sincerely,
Jim Townsend
Business Process Manager